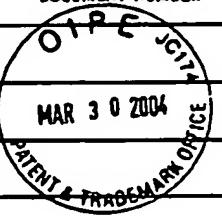


INFORMATION DISCLOSURE CITATION <i>(Use several sheets if necessary)</i>				Docket Number (Optional) PTGF-03070		Application Number 10/747,807	
				Applicant(s) Masahiro SHIMADA, et al.		Group Art Unit Not Yet Assigned	
U.S. PATENT DOCUMENTS							
EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
							
FOREIGN PATENT DOCUMENTS							
REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
YES	NO						
OTHER DOCUMENTS <i>(Including Author, Title, Date, Pertinent Pages, Etc.)</i>							
		Kazuhide Abe, et al., "High Reliable Cu Damascene Interconnects with Cu/Ti/TiN/Ti Layered Structure", Oki Technical Review, No. 184, Vol. 67, No. 3, pp. 65-68, October 2000. Miki Moriyama, et al., "Future Fabrication Techniques for Cu Wires used in Si ULSI Devices", Material Japan, Vol. 39, No. 11, pp. 901-908 (2000).					
EXAMINER 				DATE CONSIDERED 			
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609: Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							